

DATA SHEET

74ABT273A Octal D-type flip-flop

Product specification

1995 Sep 06

IC23 Data Handbook

Octal D-type flip-flop

74ABT273A

FEATURES

- Eight edge-triggered D-type flip-flops
- Buffered common clock
- Buffered asynchronous Master Reset
- Power-up reset
- See 74ABT377 for clock enable version
- See 74ABT373 for transparent latch version
- See 74ABT374 for 3-State version
- ESD protection exceeds 2000 V per Mil Std 883 Method 3015 and 200 V per machine model.

DESCRIPTION

The 74ABT273A has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ($\overline{\text{MR}}$) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the Low-to-High clock transition, is transferred to the corresponding flip-flop's Q output.

All outputs will be forced Low independent of Clock or Data inputs by a Low voltage level on the $\overline{\text{MR}}$ input. The device is useful for applications where the true output only is required and the CP and $\overline{\text{MR}}$ are common elements.

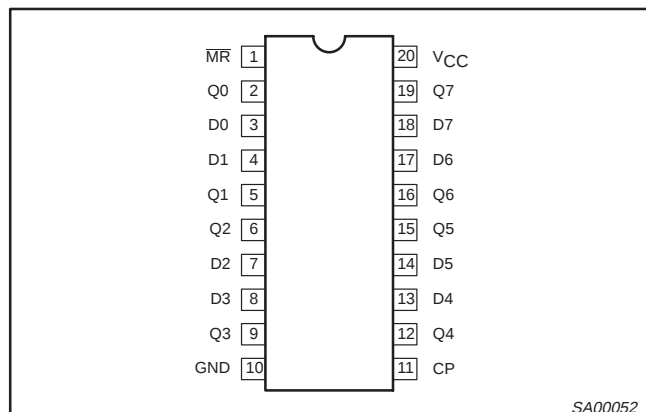
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS $T_{\text{amb}} = 25^{\circ}\text{C}$; GND = 0V	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay CP to Qn	$C_L = 50\text{pF}$; $V_{\text{CC}} = 5\text{V}$	3.0 3.4	ns
C_{IN}	Input capacitance	$V_I = 0\text{V}$ or V_{CC}	3.5	pF
I_{CCH}	Total supply current	Outputs High; $V_{\text{CC}} = 5.5\text{V}$	150	μA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	-40°C to $+85^{\circ}\text{C}$	74ABT273A N	74ABT273A N	SOT146-1
20-Pin plastic SO	-40°C to $+85^{\circ}\text{C}$	74ABT273A D	74ABT273A D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to $+85^{\circ}\text{C}$	74ABT273A DB	74ABT273A DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to $+85^{\circ}\text{C}$	74ABT273A PW	74ABT273APW DH	SOT360-1

PIN CONFIGURATION



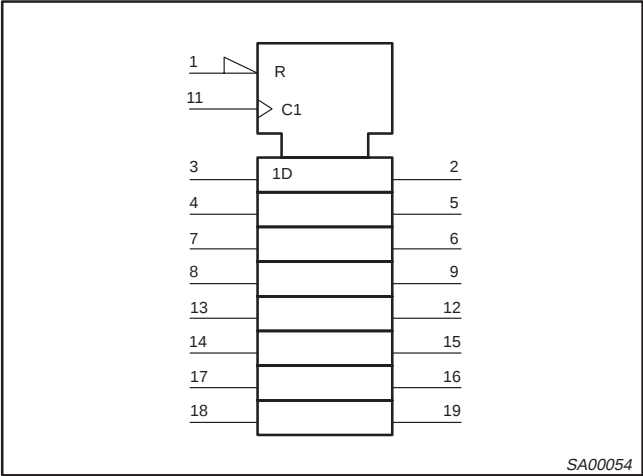
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
11	CP	Clock pulse input (active rising edge)
3, 4, 7, 8, 13, 14, 17, 18	D0 - D7	Data inputs
2, 5, 6, 9, 12, 15, 16, 19	Q0 - Q7	Data outputs
1	$\overline{\text{MR}}$	Master Reset input (active-Low)
10	GND	Ground (0V)
20	V_{CC}	Positive supply voltage

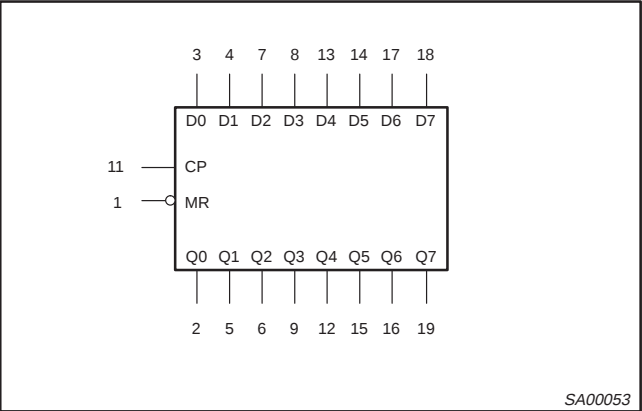
Octal D-type flip-flop

74ABT273A

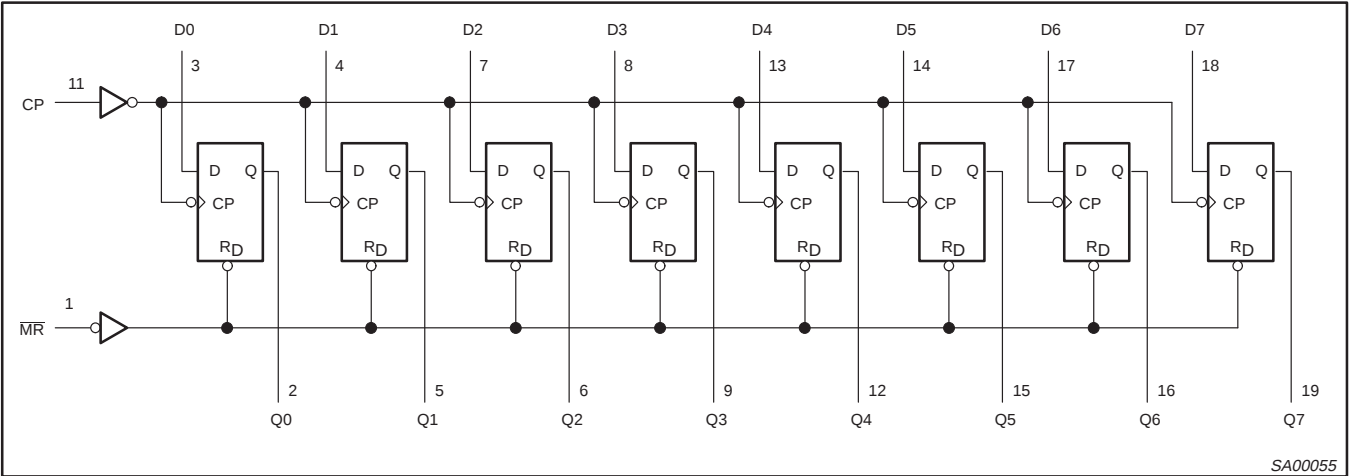
LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



LOGIC DIAGRAM



FUNCTION TABLE

INPUTS			OUTPUTS	OPERATING MODE
$\overline{MR}$	CP	Dn	Q0 - Q7	
L	X	X	L	Reset (clear)
H	$\uparrow$	h	H	Load "1"
H	$\uparrow$	l	L	Load "0"

H = High voltage level
h = High voltage level one set-up time prior to the Low-to-High clock transition
L = Low voltage level
l = Low voltage level one set-up time prior to the Low-to-High clock transition
X = Don't care
 $\uparrow$ = Low-to-High clock transition

Octal D-type flip-flop

74ABT273A

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		-0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$	-18	mA
V_I	DC input voltage ³		-1.2 to +7.0	V
I_{OK}	DC output diode current	$V_O < 0$	-50	mA
V_{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I_{OUT}	DC output current	output in Low state	128	mA
T_{Stg}	Storage temperature range		-65 to 150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V_{CC}	DC supply voltage	4.5	5.5	V
V_I	Input voltage	0	V_{CC}	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level input voltage		0.8	V
I_{OH}	High-level output current		-32	mA
I_{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T_{amb}	Operating free-air temperature range	-40	+85	°C

Octal D-type flip-flop

74ABT273A

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T _{amb} = +25°C			T _{amb} = -40°C to +85°C		
			Min	Typ	Max	Min	Max	
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA		-0.9	-1.2		-1.2	V
V _{OH}	High-level output voltage	V _{CC} = 4.5V; I _{OH} = -3mA; V _I = V _{IL} or V _{IH}	2.5	2.9		2.5		V
		V _{CC} = 5.0V; I _{OH} = -3mA; V _I = V _{IL} or V _{IH}	3.0	3.4		3.0		
		V _{CC} = 4.5V; I _{OH} = -32mA; V _I = V _{IL} or V _{IH}	2.0	2.4		2.0		
V _{OL}	Low-level output voltage	V _{CC} = 4.5V; I _{OL} = 64mA; V _I = V _{IL} or V _{IH}		0.42	0.55		0.55	V
V _{RST}	Power-up output low voltage ³	V _{CC} = 5.5V; I _O = 1mA; V _I = GND or V _{CC}		0.13	0.55		0.55	V
I _I	Input leakage current	V _{CC} = 5.5V; V _I = GND or 5.5V		±0.01	±1.0		±1.0	μA
I _{OFF}	Power-off leakage current	V _{CC} = 0.0V; V _O or V _I ≤ 4.5V		±5.0	±100		±100	μA
I _{CEX}	Output High leakage current	V _{CC} = 5.5V; V _O = 5.5V; V _I = GND or V _{CC}		5.0	50		50	μA
I _O	Output current ¹	V _{CC} = 5.5V; V _O = 2.5V	-50	-70	-180	-50	-180	mA
I _{CCH}	Quiescent supply current	V _{CC} = 5.5V; Outputs High, V _I = GND or V _{CC}		150	250		250	μA
I _{CCL}		V _{CC} = 5.5V; Outputs Low, V _I = GND or V _{CC}		24	30		30	mA
ΔI _{CC}	Additional supply current per input pin ²	V _{CC} = 5.5V; One data input at 3.4V, other inputs at V _{CC} or GND		0.5	1.5		1.5	mA

NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
2. This is the increase in supply current for each input at 3.4V .
3. For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.

AC CHARACTERISTICS

GND = 0V; $t_R = t_F = 2.5\text{ns}$; $C_L = 50\text{pF}$, $R_L = 500\Omega$

SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			T _{amb} = +25°C V _{CC} = +5.0V			T _{amb} = -40°C to +85°C V _{CC} = +5.0V ±0.5V		
			Min	Typ	Max	Min	Max	
f _{MAX}	Maximum clock frequency	1	250	350		250		MHz
t _{PLH} t _{PHL}	Propagation delay CP to Qn	1	1.5 2.0	3.0 3.4	4.0 4.6	1.5 2.0	4.8 4.8	ns
t _{PHL}	Propagation delay MR to Qn	2	2.5	4.5	6.0	2.5	6.6	ns

Octal D-type flip-flop

74ABT273A

AC SETUP REQUIREMENTS

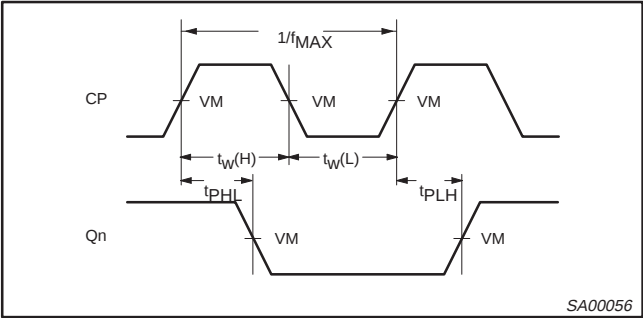
GND = 0V; $t_R = t_F = 2.5\text{ns}$; $C_L = 50\text{pF}$, $R_L = 500\Omega$

SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			$T_{\text{amb}} = +25^{\circ}\text{C}$ $V_{\text{CC}} = +5.0\text{V}$		$T_{\text{amb}} = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $V_{\text{CC}} = +5.0\text{V} \pm 0.5\text{V}$	
			Min	Typ	Min	
$t_s(\text{H})$ $t_s(\text{L})$	Setup time, High or Low Dn to CP	3	1.5 1.5	0.6 0.4	1.5 1.5	
$t_h(\text{H})$ $t_h(\text{L})$	Hold time, High or Low Dn to CP	3	0.7 0.7	-0.5 -0.5	0.7 0.7	ns
$t_w(\text{H})$ $t_w(\text{L})$	Clock pulse width High or Low	1	1.5 2.0	0.8 1.0	1.5 2.0	ns
$t_w(\text{L})$	Master Reset pulse width, Low	2	1.5	0.8	1.5	ns
t_{REC}	Recovery time MR to CP	2	1.5	0.5	1.5	ns

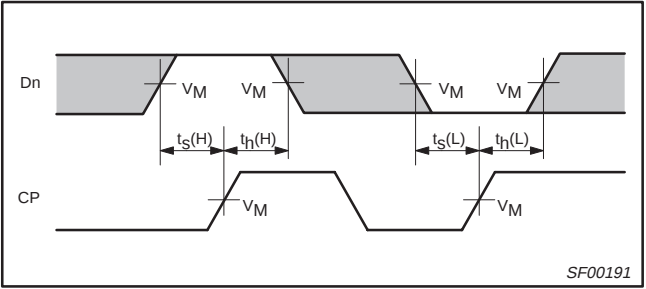
AC WAVEFORMS

$V_M = 1.5\text{V}$, $V_{\text{IN}} = \text{GND to } 3.0\text{V}$

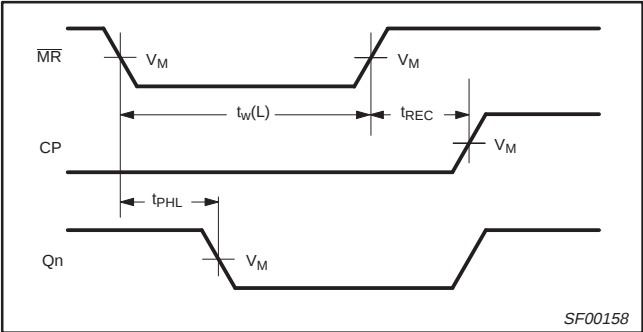
The shaded areas indicate when the input is permitted to change for predictable output performance.



Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



Waveform 3. Data Setup and Hold Times

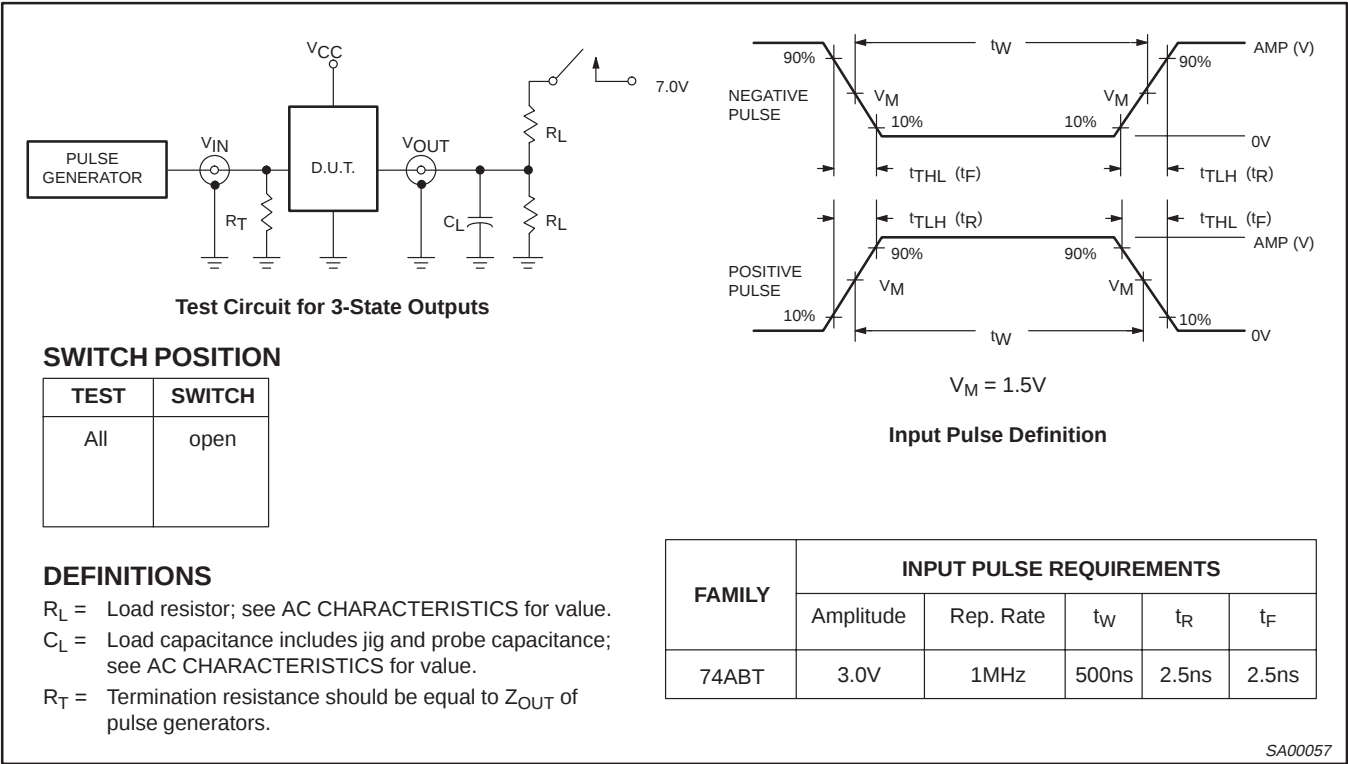


Waveform 2. Master Reset Pulse Width, Master Reset to Output Delay and Master Reset to Clock Recovery Time

Octal D-type flip-flop

74ABT273A

TEST CIRCUIT AND WAVEFORMS

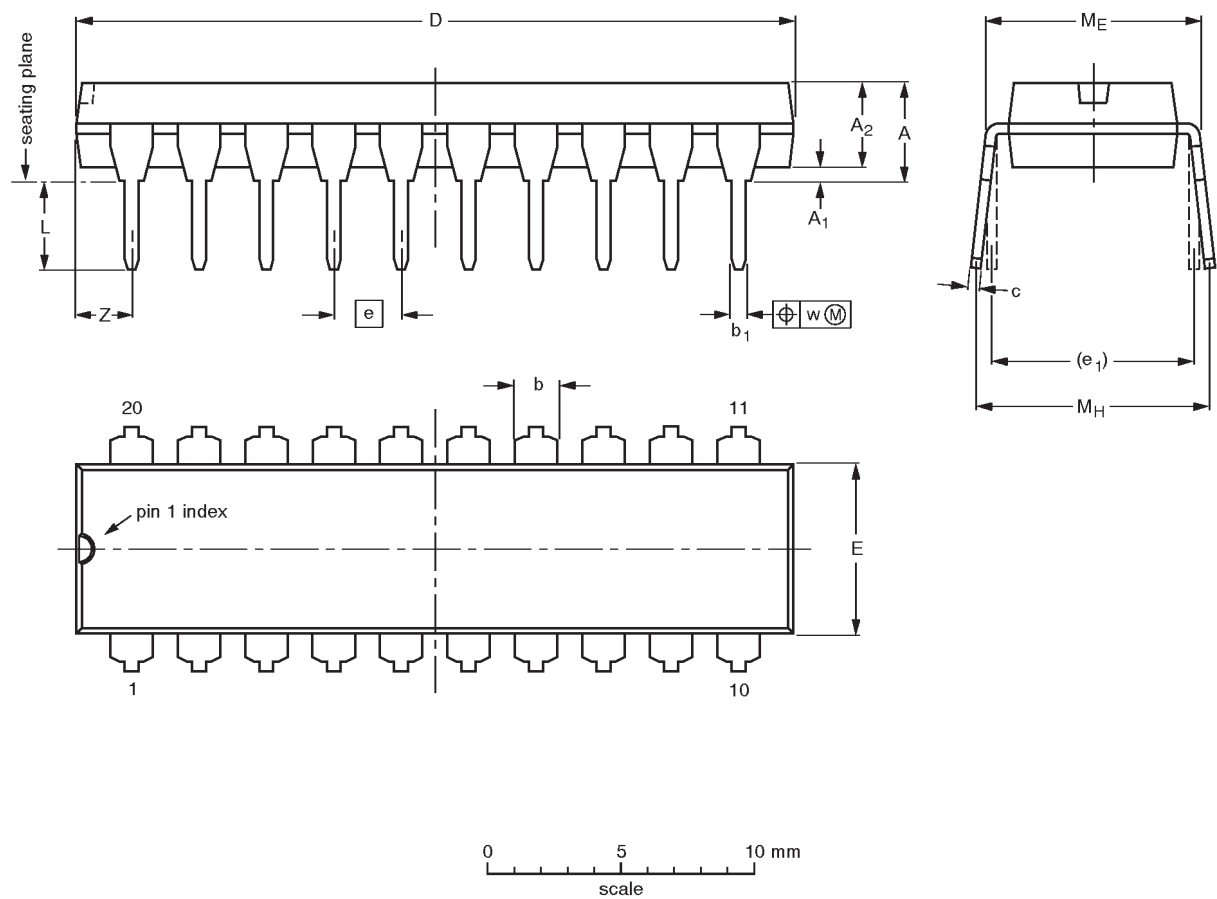


Octal D-type flip-flop

74ABT273A

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

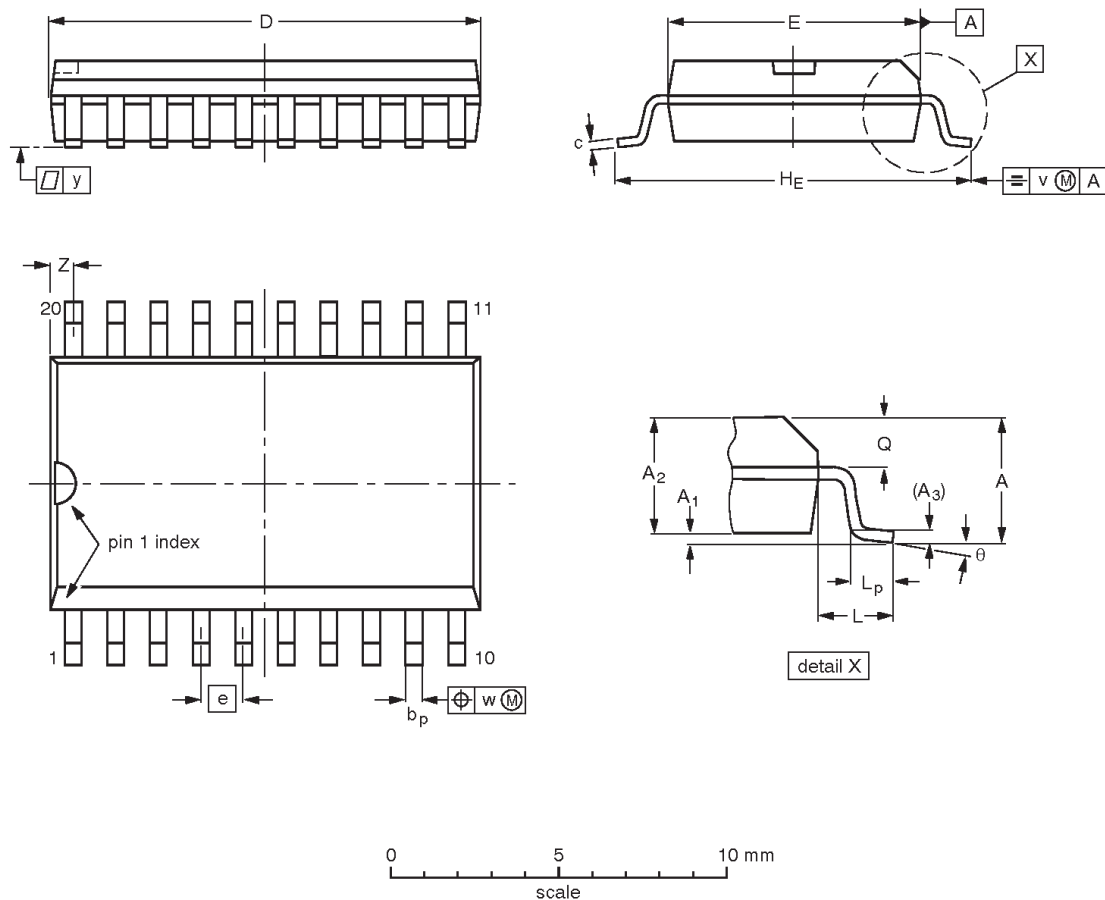
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			92-11-17 95-05-24

Octal D-type flip-flop

74ABT273A

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

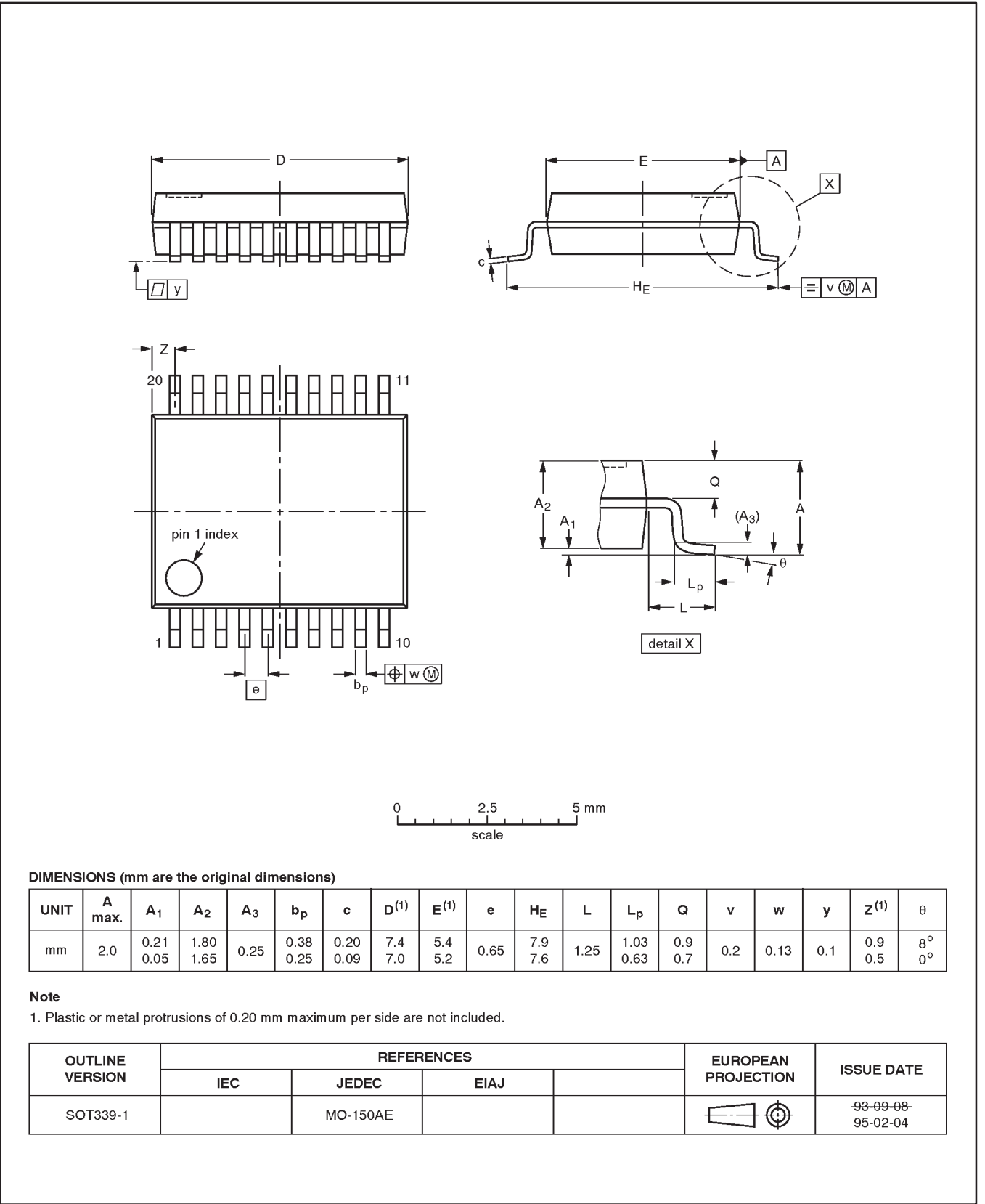
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				92-11-17 95-01-24

Octal D-type flip-flop

74ABT273A

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

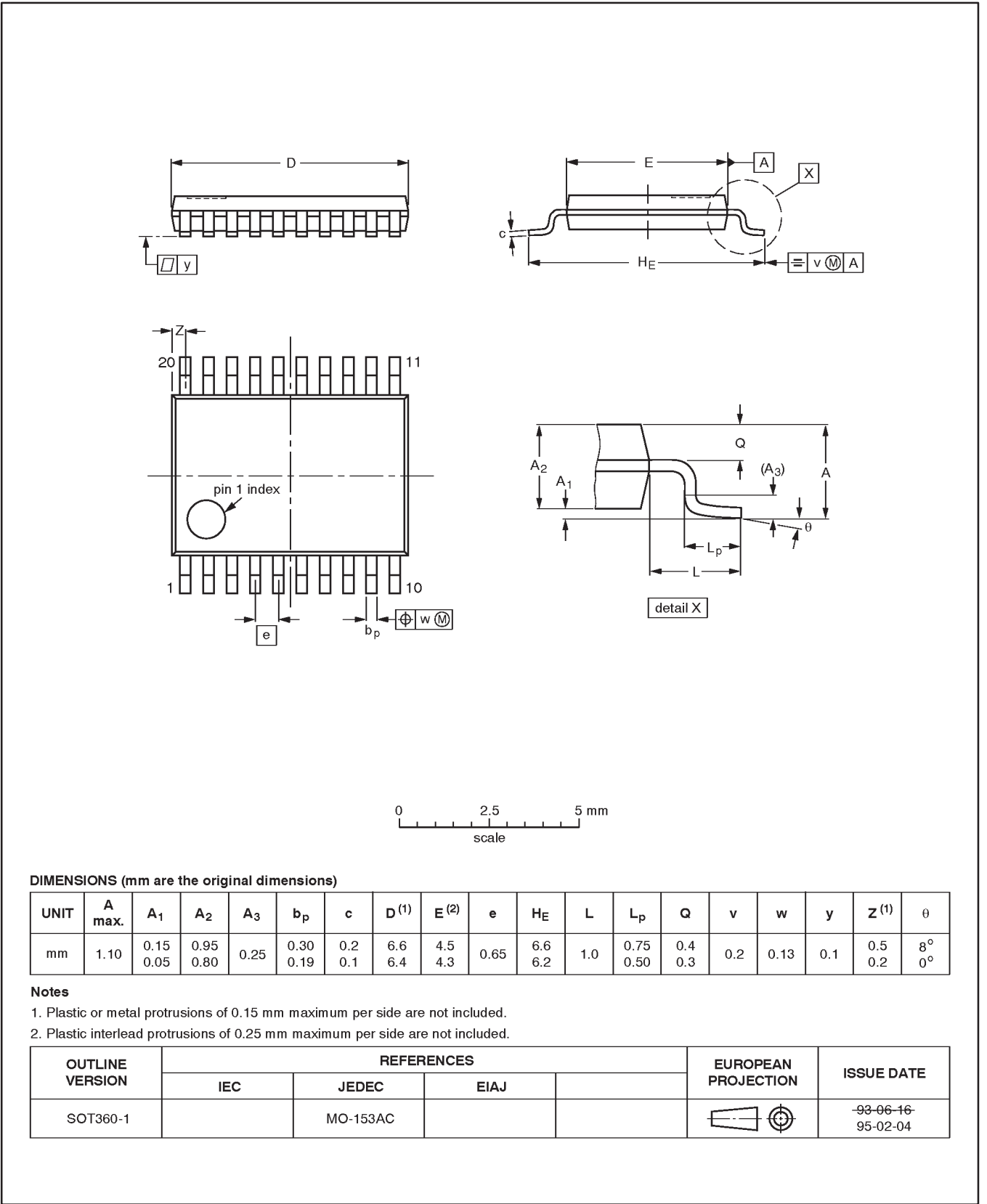


Octal D-type flip-flop

74ABT273A

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



Octal D-type flip-flop

74ABT273A

DEFINITIONS		
Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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